

### ABSTRACT

There is provided a mask for use in printing solder on a plurality of terminals formed on a substrate so as to correspond to a plurality of terminals of an IC package. The mask has openings through which the solder is applied, and the openings are larger than the terminals. Although a wiring line adjacent to the terminals may be covered with the solder, a reflow process causes the solder to be divided into a first portion and a second portion, thus preventing short-circuits between the wiring line and the terminals.